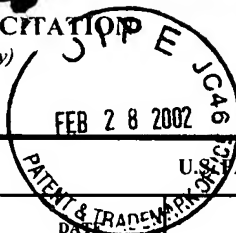


INFORMATION DISCLOSURE CITATION

(Use several sheets if necessary)



Docket Number (Optional)

PRINZ H16

Application Number

10/030,847

Applicant(s)

KRAGL

Filing Date

January 11, 2002

Group Art Unit

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
SV		5,479,540	12/26/95	Boudreau et al.	385	14	2/1/95
SV		5,577,142	11/19/96	Mueller-Fiedler et al.	385	47	11/16/95
SV		5,475,775	12/12/95	Kragl et al.	385	14	
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SV		5,774,609	6/30/98	Backlin et al.	385	49	1/27/97
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SV		5,369,529	11/29/94	Kuo et al.	359	858	7/19/93

FOREIGN PATENT DOCUMENTS

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							YES	NO
SV		WO 98/50809	11/12/98	GERMANY				
SV		DE 3929794A1	4/4/91	GERMANY				
SV		EP 0826995A1	3/4/98	EP				

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

SV		Bruehl, M. et al. "Smart-Cut: A New Silicon on Insulator Material Technology Based on Hydrogen Implantation and Wafer Bonding" Japanese Journal of Applied Physics, JP, Publication Office Japanese Journal of Applied Physics. Tokyo, Bd. 36, Nr. 3B, PART 01, March 1, 1997, pp. 1636-1641.

EXAMINER

Sunny Pak

DATE CONSIDERED

8/7/03

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.